

The LNM Institute of Information Technology, Jaipur
Department of Electronics and Communication Engineering
Modeling and Simulation of MOS Transistor (ECE4181)

End Term

Time: 180 Minutes

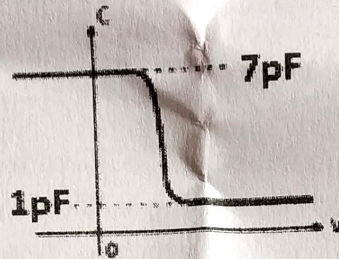
Date: 5/12/2019

Maximum Marks: 50

Instructions: All the Questions are Compulsory. Please check that there must be 5 questions in the paper, consisting of 2 printed pages.

- Q.1:** a) Draw and explain the MOS structure [1]
i. Three-terminal MOS structure in flat-band condition, with $V_{CB} = 0$. [1]
ii. The structure of (i) with a larger V_{GB} causing surface inversion [1]
iii. The structure of (ii) with a positive V_{CB} , which reduces electron concentration at the surface. [1]
iv. The structure of (iii) with further increased V_{GB} , which restores electron concentration at the surface to the level in (ii) [1]
v. Plot the conduction energy band edge vs. horizontal position along a line adjacent to the surface for the situation (i), (ii), (iii) and (iv). [2]
b) For a three terminal MOS structure plot various quantities given below characterizing the structure vs. V_{GB} and V_{GC} . (a) Surface potential; (b) gate capacitance to the rest of the structure per unit area; (c) logarithm of inversion layer charge magnitude per unit area; (d) inversion layer charge magnitude per unit area. Plot for $V_{CB}=0$ and for a V_{CB} of a given positive value. Where V_{CB} is the voltage source between the n^+ region (added to the basic MOS two terminal structure) and substrate region. [1+1+1+1]
- Q.2:** a) Explain Body effect in MOSFET. [2]
b) Explain and find the expression for pinch off voltage in a MOSFET with body effect. [2]
c) Draw the inversion layer charge vs V_{CB} (channel to body bias) for different gate to body voltage. [2]
d) Calculate the change in threshold voltage due to an applied source to body voltage $V_{CB}=1$ V. Consider an n-channel silicon MOSFET at $T = 300$ K. Assume the substrate is doped to $N_a = 3 \times 10^{16} \text{ cm}^{-3}$ and assume the oxide is silicon dioxide with a thickness of $t_{ox} = 500$ Angstrom. [4]
[Assume $n_i = 1.5 \times 10^{10} \text{ cm}^{-3}$, the relative permittivities of Si and SiO_2 are 11.7 and 3.9 respectively and $\epsilon_0 = 8.85 \times 10^{-14} \text{ F/cm}$]
- Q.3:** a) Why velocity saturation occurs in MOSFET? Derive and find the expression for drain current with velocity saturation? [1+3]
b) Briefly describes channel-length modulation and how it affects MOSFET current-voltage characteristics. [2+2]
c) Write short notes on Hot carrier effects in a Short channel MOSFET [2]

- Q.4:** a) The figure shows the high frequency capacitance-voltage (C-V) characteristics of MOS capacitor having an area of $1 \times 10^{-4} \text{ cm}^2$. Assume that the permittivity of Silicon and SiO_2 are 1×10^{-12} and $3.5 \times 10^{-13} \text{ F/cm}$ respectively. Find the gate oxide thickness in the MOS capacitor. Find the maximum depletion width in Silicon. [2+2]



- b) Briefly explain about different oxide-semiconductor interface charges in a MOS capacitor. [1+1+1+1]
- c) Calculate the flat-band voltage for an MOS capacitor with a p-type semiconductor substrate. [2]

Consider an MOS structure with a p-type semiconductor substrate doped to $N_a = 10^{16} \text{ cm}^{-3}$, a silicon dioxide insulator with a thickness of $t_{ox} = 500 \text{ Angstrom}$ and an n+ polysilicon gate. Given interface trapped Charge $Q_o = 10^{11}$ electronic charges per cm^2 . Assume $\epsilon_{ox} = 3.9$ for SiO_2 , work function difference $\phi_{ms} = -1.1 \text{ V}$.

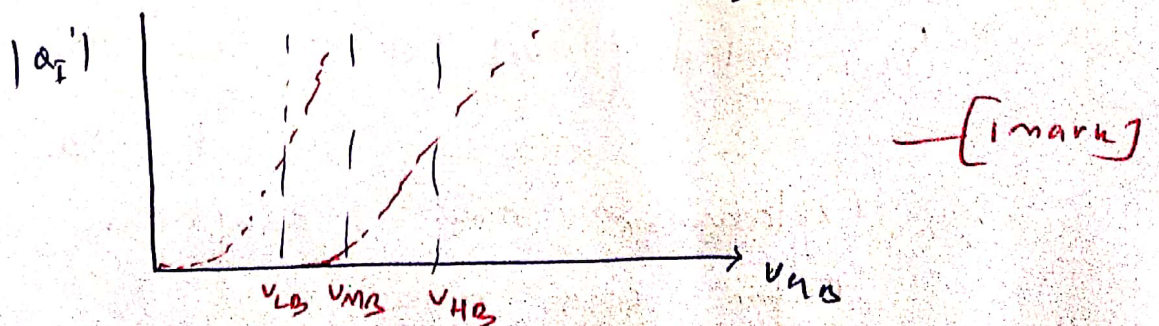
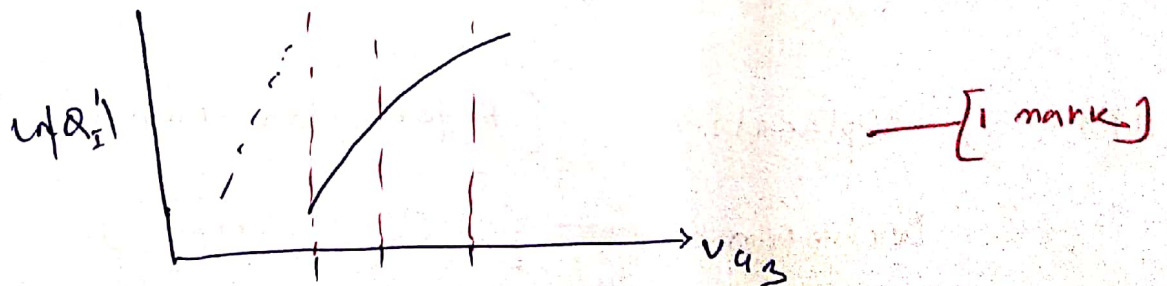
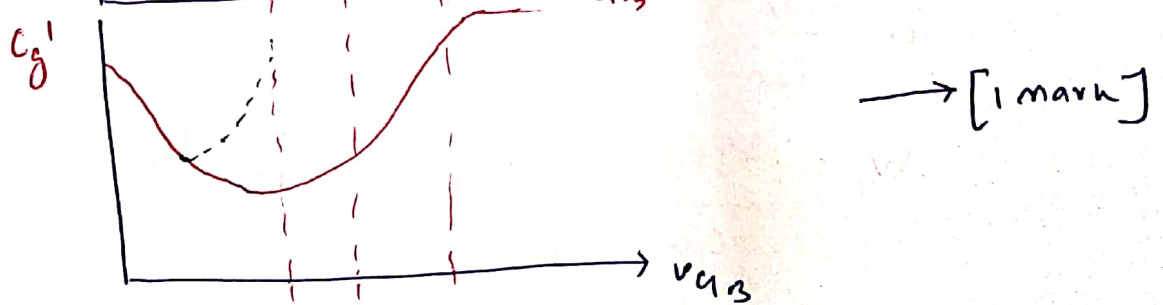
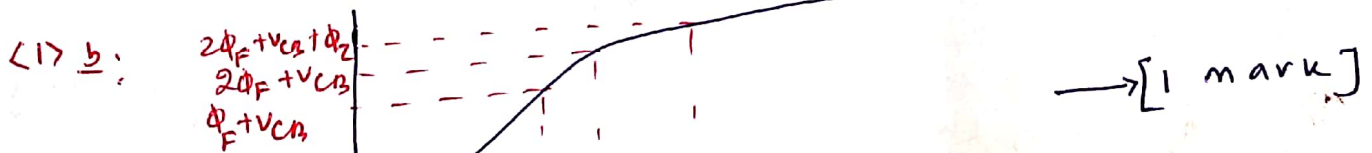
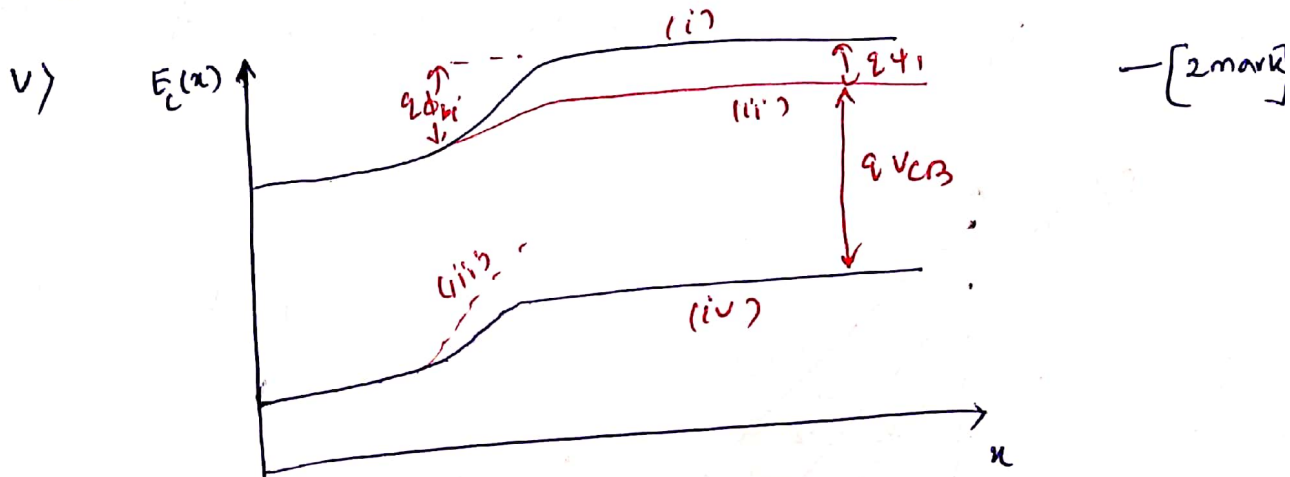
- Q.5:** a) Consider a uniformly doped GaAs pn junction at $T = 300 \text{ K}$. The junction capacitance at zero bias is $C_J(0)$ and the junction capacitance with a 10 V reverse bias voltage is $C_J(10)$. The ratio of the capacitance is [3]

$$C_J(0) / C_J(10) = 3.13$$

Also under reverse bias, the space charge width in to the p region is 0.2 of the total space charge width. Determine Built in potential (V_{bi}) and find N_d/N_a .

- b) Why Punch through occurs in MOSFET and what is its effect on drain current [3]
- c) Explain the concept of drain induced barrier lowering in a short channel device. [4]

- Q) 1 ∴ a) i) diagram, explanation (Refer class Note) — [1 mark]
- ii) " " " "
- iii) " " " "
- iv) " " " "

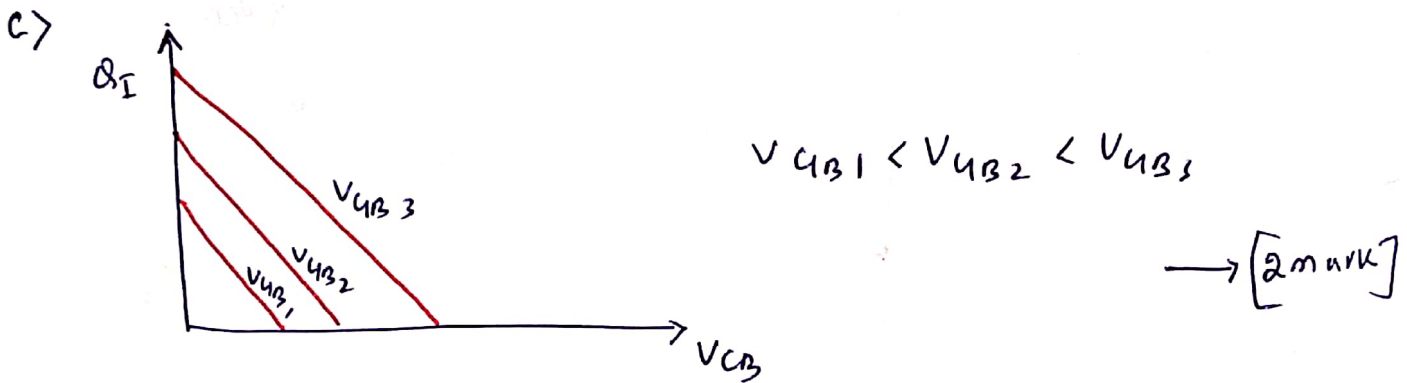


Q) 2: a) Diagram, Explanation ————— [2 mark]

$V_{CB} \uparrow \Rightarrow |Q_I'| \downarrow$, for fixed V_{GC}

b) Explanation (Refer class Note) ————— [1 mark]

$$V_p = \left(-r/2 + \sqrt{r^2/4 + V_{GB} - V_{FB}} \right)^2 - \phi_0 \rightarrow [1 \text{ mark}]$$



d) $\phi_{FP} = V_t \ln \left(\frac{N_A}{n_i} \right) = 0.376 \text{ V}$ ————— [1 mark]

$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}} = 6.9 \times 10^{-8} \text{ F/cm}^2$ ————— [1 mark]

$\Delta V_T = \frac{\sqrt{2q\epsilon_s N_A}}{C_{ox}} \left[\sqrt{2\phi_{FP} + V_{SB}} - \sqrt{2\phi_{FP}} \right]$ ————— [1 mark]

$\Delta V_T = 0.66 \text{ V}$ ————— [1 mark]

Q) 3: a) Explanation — [Refer class Note] ————— [1 mark]

Derivation — ["] ————— [3 mark]

$I_{DSN} \text{ including vel. Sat}^n = \frac{I_{DSN}, \text{ not counting } V_{sat}}{1 + V_{DS} / (LE_c)}$

b) Explanation and diagram ————— [4 mark]
Refer class note.

c) Explanation and diagram and Effects — [2 mark]

Q) 1: (a) $-C_{ox} = C_{max} = \frac{\epsilon_{ox}}{t_{ox}} = 7 \text{ pF}$ ——— 1 mark

$\Rightarrow \frac{3.5 \times 10^{-13}}{t_{ox}} = 7 \text{ pF}$

$\Rightarrow t_{ox} = 50 \text{ nm}$ ——— [1 mark]

$\frac{1}{C_{min}} = \frac{1}{C_{ox}} + \frac{1}{C_{dep}}$

$\frac{1}{1 \text{ pF}} = \frac{1}{7} + \frac{1}{C_{dep}}$ ——— [1 mark]

$\Rightarrow C_{dep} = 7/6$

$\Rightarrow \frac{\epsilon_{Si} A}{W_{dep}} = \frac{1 \times 10^{-12} \times 1 \times 10^{-4}}{W_{dep}} = 7/6$

$\Rightarrow W_{dep} = 0.857 \text{ nm}$ ——— [1 mark]

4) b: Oxide fixed charge ——— [1 mark]

oxide trapped charge ——— [1 mark]

Molecule ionic charge ——— [1 mark]

Interface trap charge ——— [1 mark]

4) c: $C_{ox} = \frac{\epsilon_{ox}}{t_{ox}} = 6.9 \times 10^{-8} \text{ F/cm}^2$ ——— [0.5]

$Q_{ss}' = (10^{11}) (1.6 \times 10^{-19}) = 1.6 \times 10^{-8} \text{ C/cm}^2$ ——— [0.5]

$V_{FB} = \phi_{ms} - \frac{Q_{ss}'}{C_{ox}} = -1.1 - \left(\frac{1.6 \times 10^{-8}}{6.9 \times 10^{-8}} \right) = -1.33 \text{ V}$ ——— [1 mark]

5) a:

$$\frac{C_j(0)}{C_j(10)} = 3.13 = \left(\frac{V_{bi} + V_R}{V_{bi}} \right)^{1/2}$$

for $V_R = 10V$, we find

$$(3.13)^2 V_{bi} = V_{bi} + 10$$

$$\Rightarrow V_{bi} = 1.14V \quad \text{--- [2 mark]}$$

$$x_p = 0.2W = 0.2(x_n + x_p)$$

$$\frac{x_p}{x_n} = 0.25 = \frac{N_d}{N_a} \quad \text{--- [1 mark]}$$

5) b:

Diagram	{	Refer	[2 mark]
Explanation		class Note	
			[1 mark]

c: Diagram --- 1 mark

Explanation --- 3 marks

(Refer class note)